

ABSTRACT OF THE DISCLOSURE

An optoelectronic device is placed in a through hole of an upper substrate and mounted on a lower substrate, which is stacked under the upper substrate. The through hole forms a focusing cup for the optoelectronic device. A metallic base plate can be inserted between the optoelectronic device and the lower substrate to enhance light reflection and heat removal. The through hole can be lined with metallic coating to enhance light reflection.

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